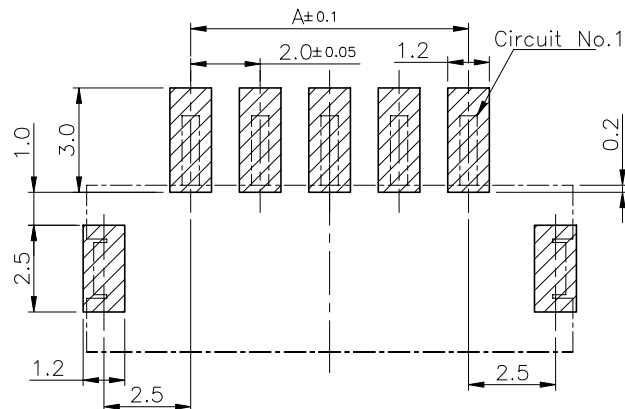
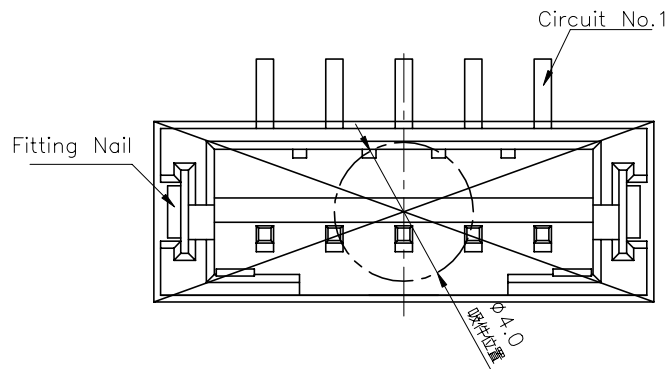
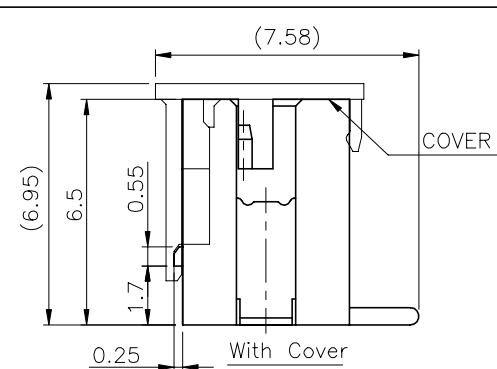
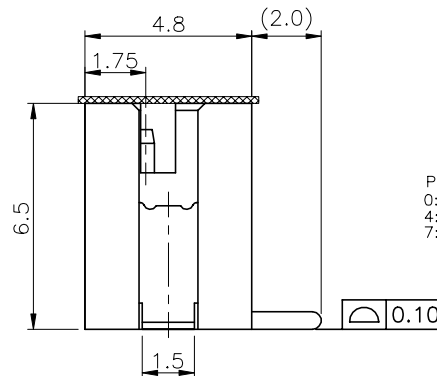
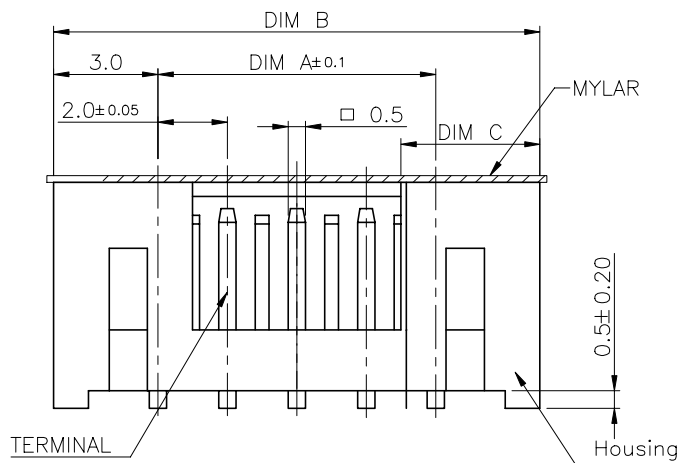




PCB PATTERN LAYOUT
GENERAL TOLERANCE ± 0.05



CKT	DIM C
2	3.50
OTHER	4.00

NOTES:

1. MATERIAL:

- 1.1 HOUSING: HALOGEN FREE PLASTIC, HIGH TEMP., UL94V-0;
- 1.2 CONTACT: COPPER ALLOY
- 1.3 FITTING NAIL: COPPER ALLOY

2. FINISH:

2.1 CONTACT:

- 50u"~100u" NICKEL UNDERPLATING OVERALL.
- 1: GOLD FLASH PLATING
- L: 80u"~150u" PURE TIN ON CONTACT AREA AND SOLDER AREA.
- N: 80u"~150u" MATT TIN ON CONTACT AREA AND SOLDER AREA.
- C: 15u" GOLD ON CONTACT AREA ,G/F ON SOLDER AREA

2.2 FITTING NAIL:

- 50u"~100u" NICKEL UNDERPLATING OVERALL.
- 1: GOLD FLASH PLATING
- L: 80u"~150u" PURE TIN ON CONTACT AREA AND SOLDER AREA.
- N: 80u"~150u" MATT TIN ON CONTACT AREA AND SOLDER AREA.
- C: GOLD FLASH PLATING

3. REFLOW SOLDER CAPABLE TO 260°C

PER ACES SPEC.

4. SPEC. PLS. REFER TO PS-50305-xxxxx-xxx

5. PACKAGE PLS. REFER TO 88290-XXXXX-U-TRP

P/N LEGEND

50310-XXX X X-CAX

Others	Housing color	HALOGEN FREE	PACKING
CA1	BLACK	HF	88290-XXXXX-U-TRP

CKTS

Packing

- 0:TAPE & REEL
- 4:TAPE & REEL WITH MYLAR
- 7:TAPE & REEL WITH COVER

Plating

- 1:GOLD FLASH
- L:PURE TIN LEAD FREE
- N:MATT TIN LEAD FREE
- C: 15u" GOLD ON CONTACT
- A: 3u" GOLD ON CONTACT

CKT	Dim A	Dim B
2	2.0	8.0
3	4.0	10.0
4	6.0	12.0
5	8.0	14.0
6	10.0	16.0
7	12.0	18.0
8	14.0	20.0
9	16.0	22.0
10	18.0	24.0
11	20.0	26.0
12	22.0	28.0
13	24.0	30.0
14	26.0	32.0
15	28.0	34.0
16	30.0	36.0
17	32.0	38.0
18	34.0	40.0
19	36.0	42.0
20	38.0	44.0

QUALITY SYMBOLS	DRAWN BY	DATE	ACES ELECTRONICS	
MAJOR	Huang,ShunSen	23/04/23	TITLE 2.0mm WTB HEADER SMT S/T S/R H=6.5mm TYPE	
CRITICAL	Lu, Jing Quan	23/04/23		
GENERAL TOLERANCES (UNLESS SPECIFIED)	APPROVED BY	DATE	UNITS	SIZE
X ± 0.5	hsieh, fu yu	23/04/23	mm	A4
X ± 0.25			SCALE	REV
XX ± 0.15			5:1	A
XXX ± 0.1			SHEET NO.	DWG NO.
ANGLES $\pm 2^\circ$			1 OF 1	50310-XXXXX-CAX